Power MOSFET –20V, 95mΩ, –2.5A, Single P-Channel

This low-profile high-power MOSFET is produced using ON Semiconductor's trench technology, which is specifically designed to minimize gate charge and ultra low on resistance. This device is suitable for applications with low gate charge driving or ultra low on resistance requirements.



- Low On-Resistance
- High Speed Switching
- 1.8V drive
- Pb-Free, Halogen Free and RoHS compliance
- Ultra small package SCH6 (1.6mm×1.6mm×0.56mmt)

Typical Applications

• DC/DC Converter

SPECIFICATIONS

ABSOLUTE MAXIMUM RATING at Ta = 25°C (Note 1, 2)

Parameter	Symbol	Value	Unit
Drain to Source Voltage	VDSS	-20	V
Gate to Source Voltage	VGSS	±10	٧
Drain Current (DC)	ID	-2.5	Α
Drain Current (Pulse) PW ≤ 10µs, duty cycle ≤ 1%	IDP	-10	Α
Power Dissipation When mounted on ceramic substrate (900mm²×0.8mm)	PD	1	W
Junction Temperature	Tj	150	°C
Storage Temperature	Tstg	-55 to +150	°C

- Note 1: Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.
 - 2 : This product is designed to "ESD immunity<200V*", so please take care when handling.
 - *Machine Model

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Value	Unit		
Junction to Ambient When mounted on ceramic substrate (900mm²×0.8mm)	$R_{\theta JA}$	125	°C/W		

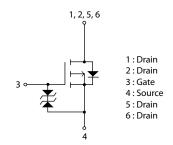


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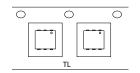
www.onsemi.com

VDSS	R _{DS} (on) Max	ID Max	
	95mΩ@ –4.5V		
-20V	138mΩ@ –2.5V	-2.5A	
	215mΩ@ –1.8V		

ELECTRICAL CONNECTION P-Channel



PACKING TYPE : TL MARKING





ORDERING INFORMATION

See detailed ordering and shipping information on page 5 of this data sheet.

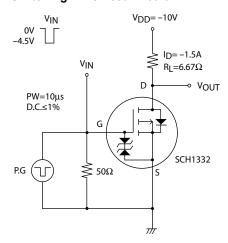
ELECTRICAL CHARACTERISTICS at Ta = 25°C (Note 3)

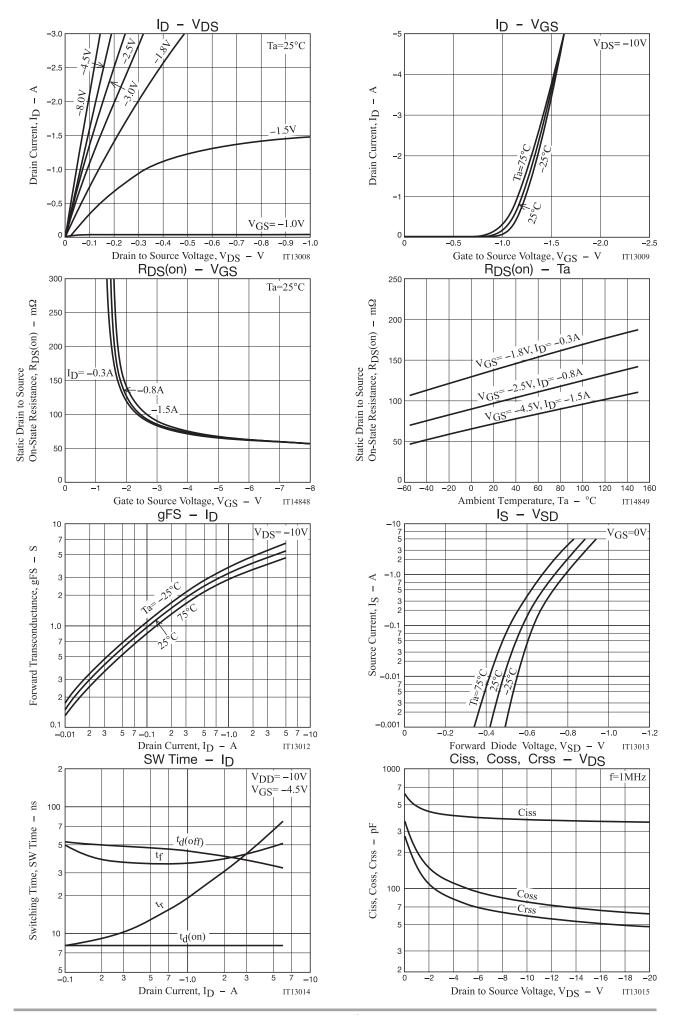
Parameter	Symbol	Conditions	Value			Unit
Farameter	Syllibol	Conditions	min	typ	max	Offic
Drain to Source Breakdown Voltage	V(BR)DSS	I _D =-1mA, V _G S=0V	-20			V
Zero-Gate Voltage Drain Current	IDSS	V _{DS} =-20V, V _{GS} =0V			-1	μΑ
Gate to Source Leakage Current	IGSS	V _{GS} =±8V, V _{DS} =0V			±10	μΑ
Gate Threshold Voltage	VGS(th)	V _{DS} =-10V, I _D =-1mA	-0.4		-1.3	V
Forward Transconductance	gFS .	V _{DS} =-10V, I _D =-1.5A	2.2	3.8		S
	R _{DS} (on)1	I _D =-1.5A, V _G S=-4.5V		73	95	mΩ
Static Drain to Source On-State Resistance	R _{DS} (on)2	I _D =-0.8A, V _G S=-2.5V		98	138	mΩ
Resistance	R _{DS} (on)3	I _D =-0.3A, V _G S=-1.8V		140	215	mΩ
Input Capacitance	Ciss			375		pF
Output Capacitance	Coss	V _{DS} =–10V, f=1MHz		77		pF
Reverse Transfer Capacitance	Crss			58		pF
Turn-ON Delay Time	t _d (on)			8.1		ns
Rise Time	t _r	On a serifical Took Classif		26		ns
Turn-OFF Delay Time	t _d (off)	See specified Test Circuit		43		ns
Fall Time	tf			37		ns
Total Gate Charge	Qg			4.6		nC
Gate to Source Charge	Qgs	V _{DS} =-10V, V _{GS} =-4.5V, I _D =-2.5A		0.8		nC
Gate to Drain "Miller" Charge	Qgd			1.3		nC
Forward Diode Voltage	V _{SD}	IS=-2.5A, VGS=0V		-0.82	-1.2	V

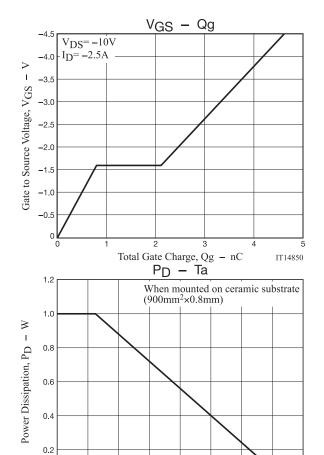
Forward Diode Voltage VSD IS=-2.5A, VGS=0V -0.82 -1.2 V

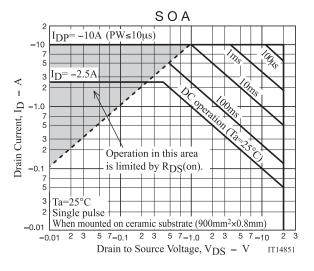
Note 3 : Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

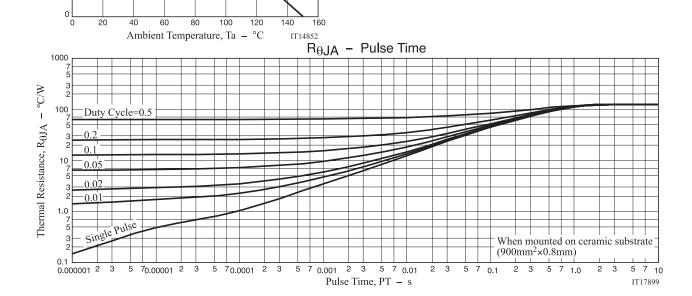
Switching Time Test Circuit





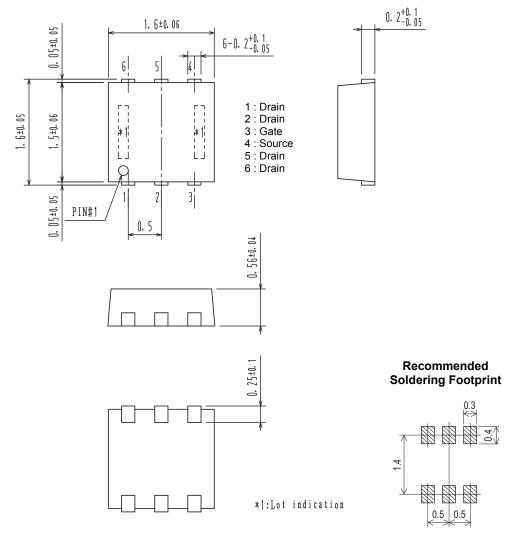






PACKAGE DIMENSIONS

unit: mm SOT-563 / SCH6 CASE 463AB ISSUE O



ORDERING INFORMATION

Device	Marking	Package	Shipping (Qty / Packing)	
SCH1332-TL-H	VII	SOT-563 / SCH6	5,000 / Tape & Reel	
SCH1332-TL-W	YH	(Pb-Free / Halogen Free)		

[†] For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D. http://www.onsemi.com/pub_link/Collateral/BRD8011-D.PDF

Note on usage: Since the SCH1332 is a MOSFET product, please avoid using this device in the vicinity of highly charged objects.

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